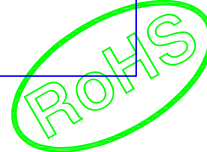
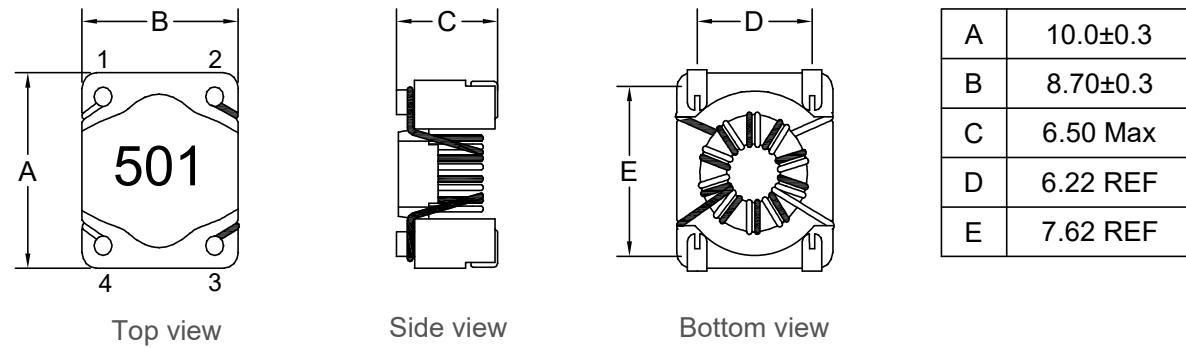


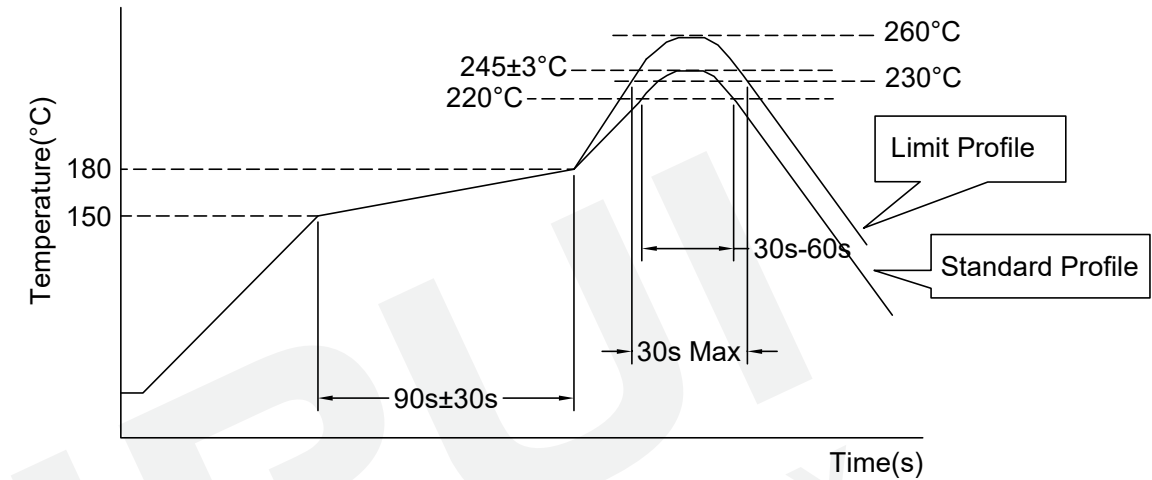
P/N: FASCM1006C-501



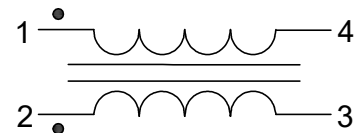
Outline Dimensions(Unit:mm)



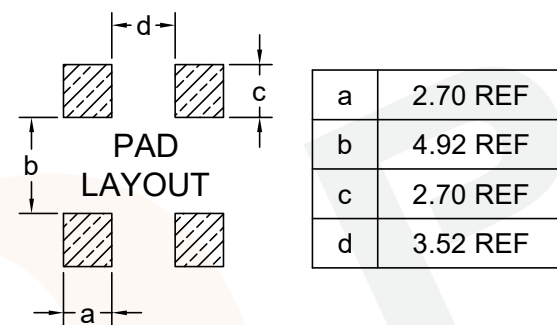
Recommended Soldering Temperature Graph.



Electronical Schematic



Suggested Pad layout



	Standard Profile	Standard Profile
Pre-heating	150~180°C,90s±30s	
Heating	above 220°C,30s-60s	above 240°C,30s Max
Peak temperature	245°C±3°C	260°C,10s
Cycle of reflow	2 times	2 times

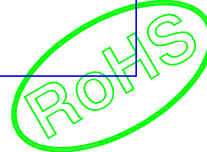
Electrical Characteristics(@25°C)

Inductance 100KHz,0.25V 1-4=2-3	DC Resistor 1-4=2-3	Rated current	Impedance Ω	Hi-Pot 1-4:2-3
500uH±40%	60mΩ Max	0.90A	800 Typ	AC300V/3mA/1S

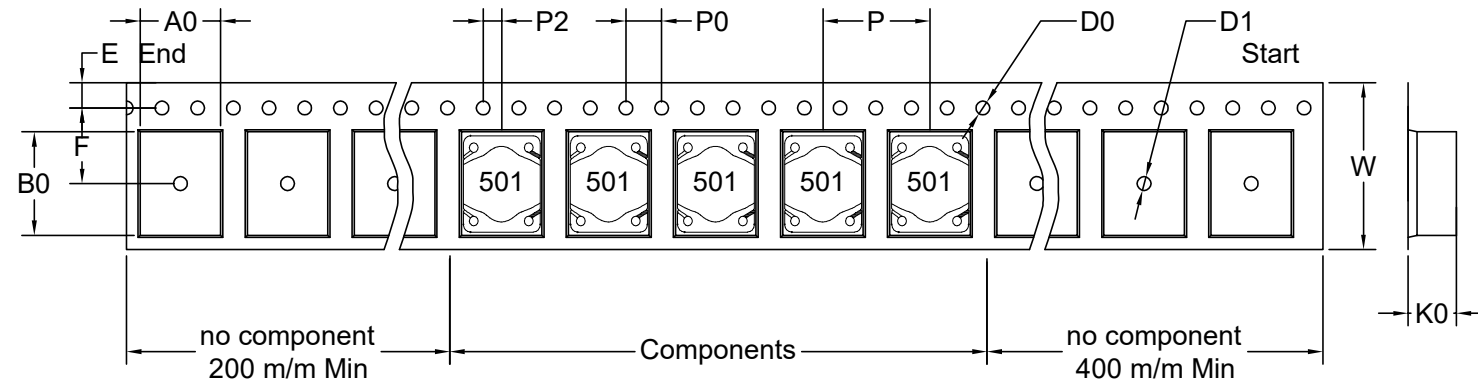
***Operating Temperature: -25°C~+85°C
 ***Storage Temperature: -25°C~+85°C
 ***Storage Humidity:RH10%~70%.

				Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX:+86-550-7831133	 Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Make: Qiumei.Liu Checked: Beson. zhan Approved: Anson. zhan	DRAWING TITLE SMD COMMON MODE CHOKES Material Number: A34006000300	Customer Name:
								Document/Rev: 1911072/00
								Specification Sheet: 1 of 4
REV	DESCRIPTION	APPD	DATE					Date of Recognition: Nov./18/2019

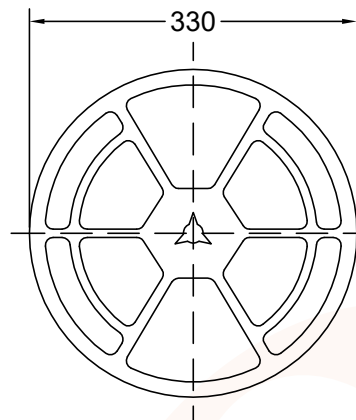
P/N: FASCM1006C-501



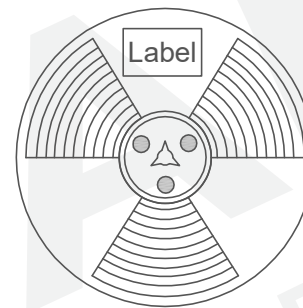
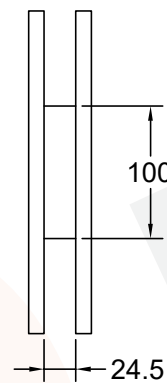
Packing Specifications(Unit:mm):



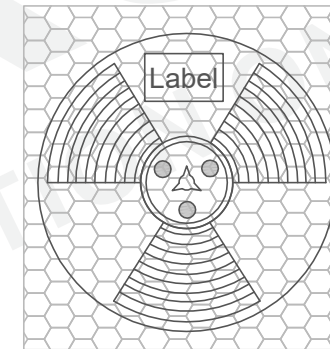
A0	9.10	F	11.5
B0	10.5	D0	1.50
P	12.0	D1	1.50
P0	4.00	K0	6.80
P2	2.00	W	24.0
E	1.75		



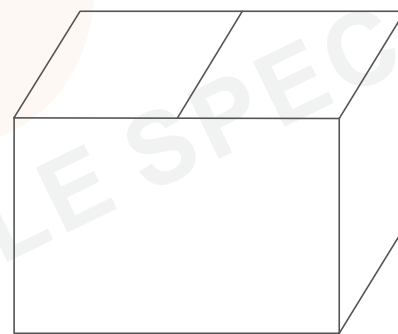
Quantity:500pcs/Reel



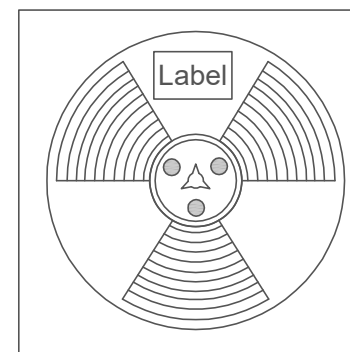
Quantity: 500pcs



PE bag



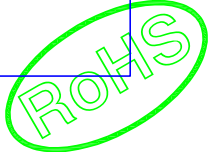
Outer cases: 2500pcs/box
Insufficient boxes filled with inner boxes or fillers



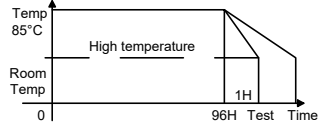
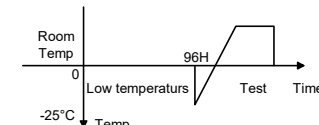
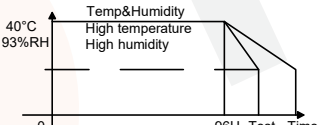
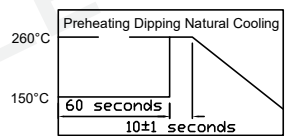
Inner box
Quantity: 500 pcs/box

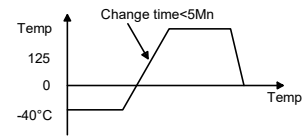
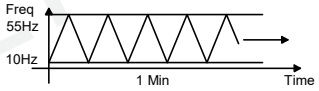
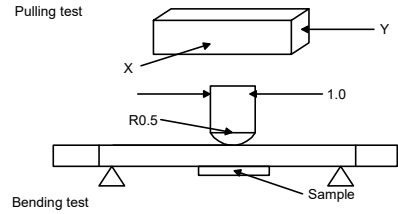
				Tianchang Fuan Electronic Co Ltd www.fuantronics.net TEL: +86-550-7814888 FAX:+86-550-7831133	Tolerances unless otherwise specified: (.X)±0.50 (.XX)±0.25 Unit of measurement: mm	Make: Qiumei.Liu	DRAWING TITLE SMD COMMON MODE CHOKES Material Number: A34006000300	Customer Name:
						Checked: Beson. zhan		Document/Rev: 1911072/00
REV	DESCRIPTION	APPD	DATE			Approved: Anson. zhan		Specification Sheet: 2 of 4

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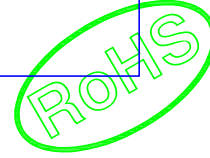
Reliability Testing:

Ltem	Specified value	Test methods
High temperature Storage test Reference documents: MIL-STD-202G Method 108A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$.	Temperature: $85 \pm 2^\circ\text{C}$ Time: 96 ± 2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Low temperature Storage test. Referencedocuments: IEC 68-2-1A 6.1 6.2	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$.	Temperature: $25 \pm 2^\circ\text{C}$ Time: 96 ± 2 hours. Tested not less than 1 hour, not more than 2 hours at room temperature. 
Humidity test Reference Documents: MIL-STD-202G Method 103B	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$.	1.Dry oven at a temperature of $40^\circ \pm 5^\circ\text{C}$ for 24 hours. 2.Measurements At the end of this period 3.Exposure:Temperature: $40 \pm 2^\circ\text{C}$,Humidity: $93 \pm 3\% \text{RH}$ Time: 96 ± 2 hours. 4.Tested while the specimens are still in the chamber. 5.Tested not less than 1 hour, nor more than 2 hours at room temperature. 
Heat endurance of Reflow soldering	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$.	Preheat: 150°C ,60 second. Solder: Sn/Ag/Cu . Solder:Temperature: $260 \pm 5^\circ\text{C}$. Flux:Rosin flux. Reflow peak time 10 second at 260°C 

Ltem	Specified value	Test methods
Thermal shock test Reference documents: MIL-STD-202G Method 107G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$. For T:weighe $\leq 28\text{g}$:15 Min 28g \leq weight $\leq 136\text{g}$:30 Min	First- 40°C for T time,next+ 125°C Ttime as 1 cycle. Go through 20 cycles. 
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002B	Terminals area must have 95% Min. Solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^\circ\text{C}$ for 5 second. Soler: $\text{Sn}(93.5)\text{Ag}(3.5)$. Flux:Rosin flux.
Vibration test Reference documents: MIL-STD-202G Method 201A	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$.	Apply frequency 10~55Hz. 0.75mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours). 
Drop test Reference documents: MIL-STD-202G Method 203G	1.No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$. 3. $\Delta Q/Q \leq 30\%$. 4. $\Delta DCR/DCR \leq 10\%$. For T:weighe $\leq 28\text{g}$:15 Min 28g \leq weight $\leq 136\text{g}$:30 Min	Packaged & Drop down from 1m with $981\text{m/s}^2(100\text{G})$ attitude in 1 angle 1 ridges & 2 surfaces orientations.
Terminal strength push test Reference documents: JIS C 5321:1997	Pulling test: DEFINE:A:sectional area of terminal $A \leq 8(\text{Sq M})$ Force $\geq 5\text{N}$ time:30sec $8(\text{Sq M}) < A \leq 20(\text{Sq M})$ Force $\geq 10\text{N}$ time:10sec $20(\text{Sq M}) < A$ force $\geq 20\text{N}$ time:10sec Bending test: Soldering the products on PCB,after the pulling testand bending test, terminal should not pull off	Bend the testing PCB at middle point, the deflection shall be 2mm 

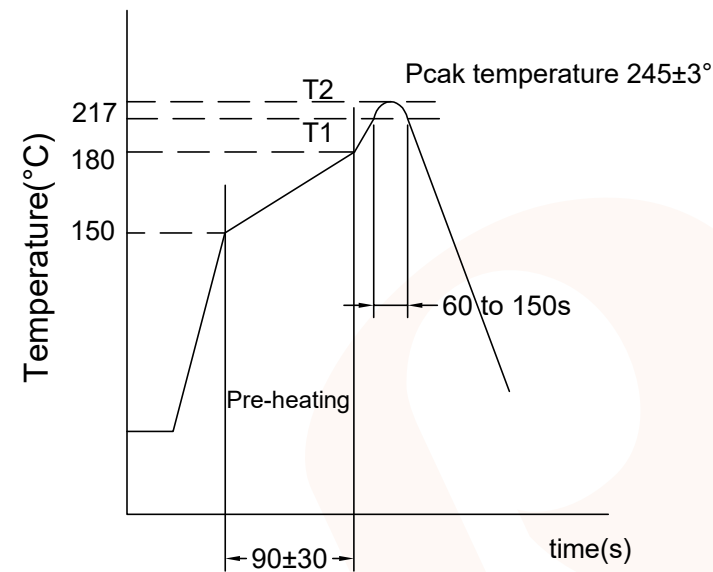
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Ltem	Specified value	Test methods
Resistance to solvent test Reference documents: IEC 68-2-45:1993	No case deformation or change in appearance, or obliteration of marking	To dip parts into IPA solvent for 5±0.5Min, then drying them at room temp for 5 Min, at last, to brushing making 10 times.
Electronic characteristic test of major products	Refer to catalogue of specific products	Refer to catalogue of specific products
Overload test Reference documents:	1. During the test no smoke, no peculiar smell, no fire	Apply twice as rated current for 5 minutes.

Recommended solderability temperature profile:



Use rosin-based flux
Don't use high acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
Use lead-free solder, use Sn-3.0Ag-0.5Cu solder
Standard thickness of solder paste: 0.12-0.15mm

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